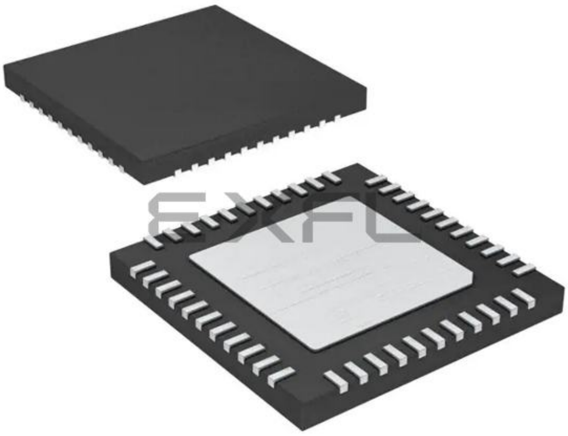
Microchip Technology - DSPIC33EP16GS504T-E/ML Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 19x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep16gs504t-e-ml

TABLE 4-11: PWM GENERATOR 4 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PWMCON4	0C80	FLTSTAT	CLSTAT	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB	MDCS	DTC1	DTC0	—	—	MTBS	CAM	XPRES	IUE	0000
IOCON4	0C82	PENH	PENL	POLH	POLL	PMOD1	PMOD0	OVRENH	OVRENL	OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC	C000
FCLCON4	0C84	IFLTMOD	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL	CLMOD	FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL	FLTMOD1	FLTMOD0	00F8
PDC4	0C86	PWM4 Generator Duty Cycle Register (PDC4<15:0>)																0000
PHASE4	0C88	PWM4 Primary Phase-Shift or Independent Time Base Period Register (PHASE4<15:0>)																0000
DTR4	0C8A	—	—	PWM4 Dead-Time Register (DTR4<13:0>)														0000
ALTDTR4	0C8C	—	—	PWM4 Alternate Dead-Time Register (ALTDTR4<13:0>)														0000
SDC4	0C8E	PWM4 Secondary Duty Cycle Register (SDC4<15:0>)																0000
SPHASE4	0C90	PWM4 Secondary Phase-Shift Register (SPHASE4<15:0>)																0000
TRIG4	0C92	PWM4 Primary Trigger Compare Value Register (TRGCMP<12:0>)													—	—	—	0000
TRGCON4	0C94	TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—	DTM	—	TRGSTRT5	TRGSTRT4	TRGSTRT3	TRGSTRT2	TRGSTRT1	TRGSTRT0	0000
STRIG4	0C96	PWM4 Secondary Trigger Compare Value Register (STRGCMP<12:0>)													—	—	—	0000
PWMCAP4	0C98	PWM4 Primary Time Base Capture Register (PWMCAP<12:0>)													—	—	—	0000
LEBCON4	0C9A	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—	—	—	BCH	BCL	BPHH	BPHL	BPLH	BPLL	0000
LEBDLY4	0C9C	—	—	—	—	PWM4 Leading-Edge Blanking Delay Register (LEB<8:0>)									—	—	—	0000
AUXCON4	0C9E	HRPDIS	HRDDIS	—	—	BLANKSEL3	BLANKSEL2	BLANKSEL1	BLANKSEL0	—	—	CHOPSEL3	CHOPSEL2	CHOPSEL1	CHOPSEL0	CHOPHEN	CHOPLEN	0000

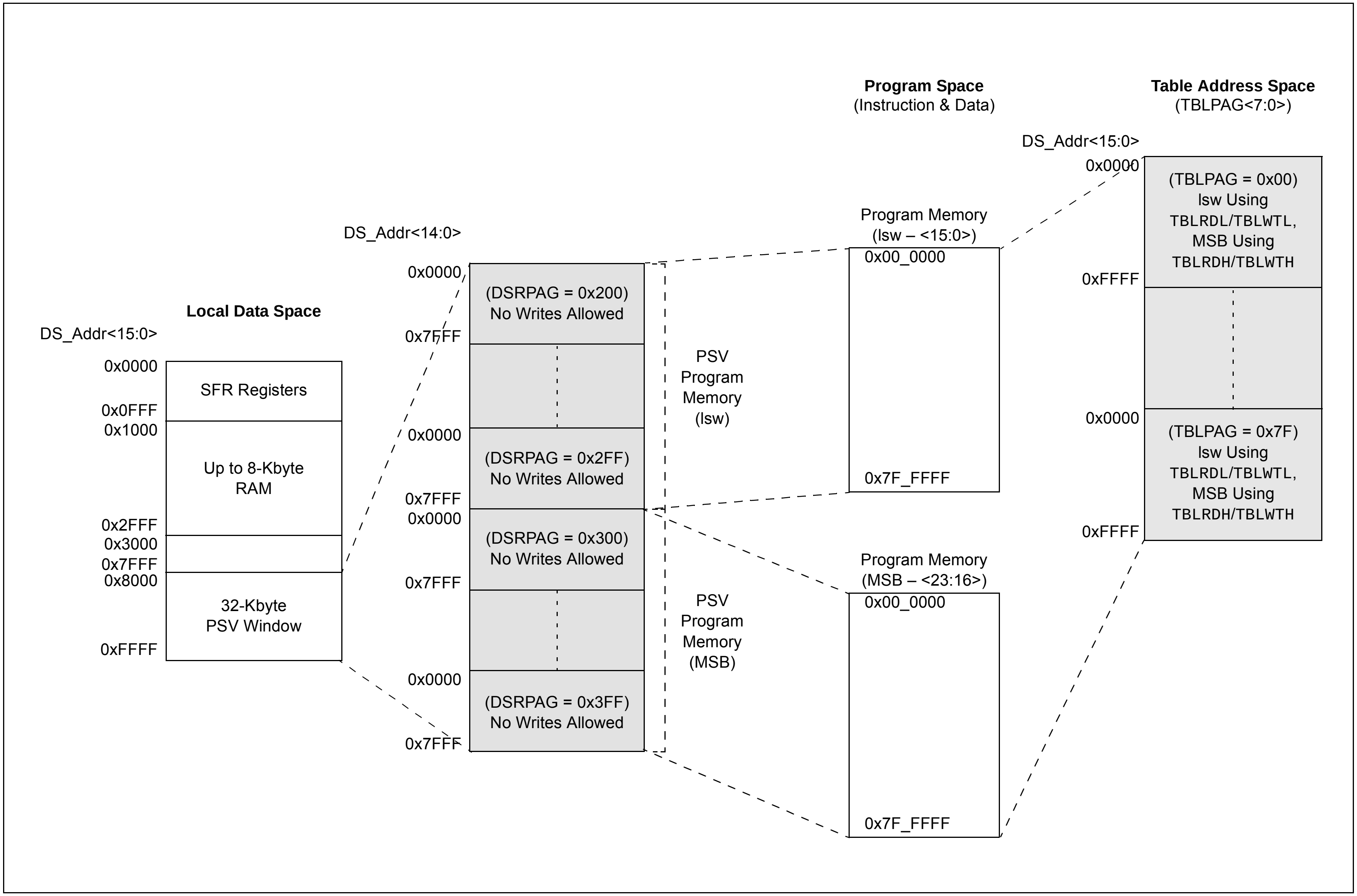
Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

TABLE 4-12: PWM GENERATOR 5 REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PWMCON5	0CA0	FLTSTAT	CLSTAT	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB	MDCS	DTC1	DTC0	—	—	MTBS	CAM	XPRES	IUE	0000
IOCON5	0CA2	PENH	PENL	POLH	POLL	PMOD1	PMOD0	OVRENH	OVRENL	OVRDAT1	OVRDAT0	FLTDAT1	FLTDAT0	CLDAT1	CLDAT0	SWAP	OSYNC	C000
FCLCON5	0CA4	IFLTMOD	CLSRC4	CLSRC3	CLSRC2	CLSRC1	CLSRC0	CLPOL	CLMOD	FLTSRC4	FLTSRC3	FLTSRC2	FLTSRC1	FLTSRC0	FLTPOL	FLTMOD1	FLTMOD0	00F8
PDC5	0CA6	PWM5 Generator Duty Cycle Register (PDC5<15:0>)																0000
PHASE5	0CA8	PWM5 Primary Phase-Shift or Independent Time Base Period Register (PHASE5<15:0>)																0000
DTR5	0CAA	—	—	PWM5 Dead-Time Register (DTR5<13:0>)														0000
ALTDTR5	0CAC	—	—	PWM5 Alternate Dead-Time Register (ALTDTR5<13:0>)														0000
SDC5	0CAE	PWM5 Secondary Duty Cycle Register (SDC5<15:0>)																0000
SPHASE5	0CB0	PWM5 Secondary Phase-Shift Register (SPHASE5<15:0>)																0000
TRIG5	0CB2	PWM5 Primary Trigger Compare Value Register (TRGCMP<12:0>)													—	—	—	0000
TRGCON5	0CB4	TRGDIV3	TRGDIV2	TRGDIV1	TRGDIV0	—	—	—	—	DTM	—	TRGSTRT5	TRGSTRT4	TRGSTRT3	TRGSTRT2	TRGSTRT1	TRGSTRT0	0000
STRIG5	0CB6	PWM5 Secondary Trigger Compare Value Register (STRGCMP<12:0>)													—	—	—	0000
PWMCAP5	0CB8	PWM5 Primary Time Base Capture Register (PWMCAP<12:0>)													—	—	—	0000
LEBCON5	0CBA	PHR	PHF	PLR	PLF	FLTLEBEN	CLLEBEN	—	—	—	—	BCH	BCL	BPHH	BPHL	BPLH	BPLL	0000
LEBDLY5	0CBC	—	—	—	—	PWM5 Leading-Edge Blanking Delay Register (LEB<8:0>)									—	—	—	0000
AUXCON5	0CBE	HRPDIS	HRDDIS	—	—	BLANKSEL3	BLANKSEL2	BLANKSEL1	BLANKSEL0	—	—	CHOPSEL3	CHOPSEL2	CHOPSEL1	CHOPSEL0	CHOPHEN	CHOPLEN	0000

Legend: — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

FIGURE 4-10: PAGED DATA MEMORY SPACE



5.4 Dual Partition Flash Configuration

For dsPIC33EP64GS50X devices operating in Dual Partition Flash Program Memory modes, the Inactive Partition can be erased and programmed without stalling the processor. The same programming algorithms are used for programming and erasing the Flash in the Inactive Partition, as described in **Section 5.2 "RTSP Operation"**. On top of the page erase option, the entire Flash memory of the Inactive Partition can be erased by configuring the NVMOP<3:0> bits in the NVMCON register.

Note 1: The application software to be loaded into the Inactive Partition will have the address of the Active Partition. The bootloader firmware will need to offset the address by 0x400000 in order to write to the Inactive Partition.

5.4.1 FLASH PARTITION SWAPPING

The Boot Sequence Number is used for determining the Active Partition at start-up and is encoded within the FBTSEQ Configuration register bits. Unlike most Configuration registers, which only utilize the lower 16 bits of the program memory, FBTSEQ is a 24-bit Configuration Word. The Boot Sequence Number (BSEQ) is a 12-bit value and is stored in FBTSEQ twice. The true value is stored in bits, FBTSEQ<11:0>, and its complement is stored in bits, FBTSEQ<23:12>. At device Reset, the sequence numbers are read and the partition with the lowest sequence number becomes the Active Partition. If one of the Boot Sequence Numbers is invalid, the device will select the partition with the valid Boot Sequence Number, or default to Partition 1 if both sequence numbers are invalid. See **Section 23.0 "Special Features"** for more information.

The `BOOTSWP` instruction provides an alternative means of swapping the Active and Inactive Partitions (soft swap) without the need for a device Reset. The `BOOTSWP` must always be followed by a `GOTO` instruction. The `BOOTSWP` instruction swaps the Active and Inactive Partitions, and the PC vectors to the location specified by the `GOTO` instruction in the newly Active Partition.

It is important to note that interrupts should temporarily be disabled while performing the soft swap sequence and that after the partition swap, all peripherals and interrupts which were enabled remain enabled. Additionally, the RAM and stack will maintain state after the switch. As a result, it is recommended that applications using soft swaps jump to a routine that will reinitialize the device in order to ensure the firmware runs as expected. The Configuration registers will have no effect during a soft swap.

For robustness of operation, in order to execute the `BOOTSWP` instruction, it is necessary to execute the NVM unlocking sequence as follows:

1. Write 0x55 to NVMKEY.
2. Write 0xAA to NVMKEY.
3. Execute the `BOOTSWP` instruction.

If the unlocking sequence is not performed, the `BOOTSWP` instruction will be executed as a forced `NOP` and a `GOTO` instruction, following the `BOOTSWP` instruction, will be executed, causing the PC to jump to that location in the current operating partition.

The SFTSWP and P2ACTIV bits in the NVMCON register are used to determine a successful swap of the Active and Inactive Partitions, as well as which partition is active. After the `BOOTSWP` and `GOTO` instructions, the SFTSWP bit should be polled to verify the partition swap has occurred and then cleared for the next panel swap event.

5.4.2 DUAL PARTITION MODES

While operating in Dual Partition mode, dsPIC33EP64GS50X family devices have the option for both partitions to have their own defined security segments, as shown in Figure 23-4. Alternatively, the device can operate in Protected Dual Partition mode, where Partition 1 becomes permanently erase/write-protected. Protected Dual Partition mode allows for a "Factory Default" mode, which provides a fail-safe backup image to be stored in Partition 1.

dsPIC33EP64GS50X family devices can also operate in Privileged Dual Partition mode, where additional security protections are implemented to allow for protection of intellectual property when multiple parties have software within the device. In Privileged Dual Partition mode, both partitions place additional restrictions on the BSLIM register. These prevent changes to the size of the Boot Segment and General Segment, ensuring that neither segment will be altered.

5.5 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

5.5.1 KEY RESOURCES

- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

REGISTER 9-7: PMD8: PERIPHERAL MODULE DISABLE CONTROL REGISTER 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	U-0
—	—	—	—	—	PGA2MD	ABGMD	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	U-0
—	—	—	—	—	—	CCSMD	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘`0`’

bit 10 **PGA2MD:** PGA2 Module Disable bit
`1` = PGA2 module is disabled
`0` = PGA2 module is enabled

bit 9 **ABGMD:** Band Gap Reference Voltage Disable bit
`1` = Band gap reference voltage is disabled
`0` = Band gap reference voltage is enabled

bit 8-2 **Unimplemented:** Read as ‘`0`’

bit 1 **CCSMD:** Constant-Current Source Module Disable bit
`1` = Constant-current source module is disabled
`0` = Constant-current source module is enabled

bit 0 **Unimplemented:** Read as ‘`0`’

TABLE 10-1: SELECTABLE INPUT SOURCES (MAPS INPUT TO FUNCTION)

Input Name(1)	Function Name	Register	Configuration Bits
External Interrupt 1	INT1	RPINR0	INT1R<7:0>
External Interrupt 2	INT2	RPINR1	INT2R<7:0>
Timer1 External Clock	T1CK	RPINR2	T1CKR<7:0>
Timer2 External Clock	T2CK	RPINR3	T2CKR<7:0>
Timer3 External Clock	T3CK	RPINR3	T3CKR<7:0>
Input Capture 1	IC1	RPINR7	IC1R<7:0>
Input Capture 2	IC2	RPINR7	IC2R<7:0>
Input Capture 3	IC3	RPINR8	IC3R<7:0>
Input Capture 4	IC4	RPINR8	IC4R<7:0>
Output Compare Fault A	OCFA	RPINR11	OCFAR<7:0>
PWM Fault 1	FLT1	RPINR12	FLT1R<7:0>
PWM Fault 2	FLT2	RPINR12	FLT2R<7:0>
PWM Fault 3	FLT3	RPINR13	FLT3R<7:0>
PWM Fault 4	FLT4	RPINR13	FLT4R<7:0>
UART1 Receive	U1RX	RPINR18	U1RXR<7:0>
UART1 Clear-to-Send	$\overline{\text{U1CTS}}$	RPINR18	U1CTSR<7:0>
UART2 Receive	U2RX	RPINR19	U2RXR<7:0>
UART2 Clear-to-Send	$\overline{\text{U2CTS}}$	RPINR19	U2CTSR<7:0>
SPI1 Data Input	SDI1	RPINR20	SDI1R<7:0>
SPI1 Clock Input	SCK1	RPINR20	SCK1R<7:0>
SPI1 Slave Select	$\overline{\text{SS1}}$	RPINR21	SS1R<7:0>
SPI2 Data Input	SDI2	RPINR22	SDI2R<7:0>
SPI2 Clock Input	SCK2	RPINR22	SCK2R<7:0>
SPI2 Slave Select	$\overline{\text{SS2}}$	RPINR23	SS2R<7:0>
PWM Synch Input 1	SYNCI1	RPINR37	SYNCI1R<7:0>
PWM Synch Input 2	SYNCI2	RPINR38	SYNCI2R<7:0>
PWM Fault 5	FLT5	RPINR42	FLT5R<7:0>
PWM Fault 6	FLT6	RPINR42	FLT6R<7:0>
PWM Fault 7	FLT7	RPINR43	FLT7R<7:0>
PWM Fault 8	FLT8	RPINR43	FLT8R<7:0>

Note 1: Unless otherwise noted, all inputs use the Schmitt Trigger input buffers.

REGISTER 10-3: RPINR2: PERIPHERAL PIN SELECT INPUT REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
T1CKR7	T1CKR6	T1CKR5	T1CKR4	T1CKR3	T1CKR2	T1CKR1	T1CKR0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **T1CKR<7:0>:** Assign Timer1 External Clock (T1CK) to the Corresponding RPn Pin bits

`10110101` = Input tied to RP181
`10110100` = Input tied to RP180
•
•
•
`00000001` = Input tied to RP1
`00000000` = Input tied to Vss

bit 7-0 **Unimplemented:** Read as ‘`0`’

14.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare with Dedicated Timer"** (DS70005159) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The output compare module can select one of six available clock sources for its time base. The module compares the value of the timer with the value of one or two Compare registers, depending on the operating mode selected. The state of the output pin changes when the timer value matches the Compare register value. The output compare module generates either a single output pulse, or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events.

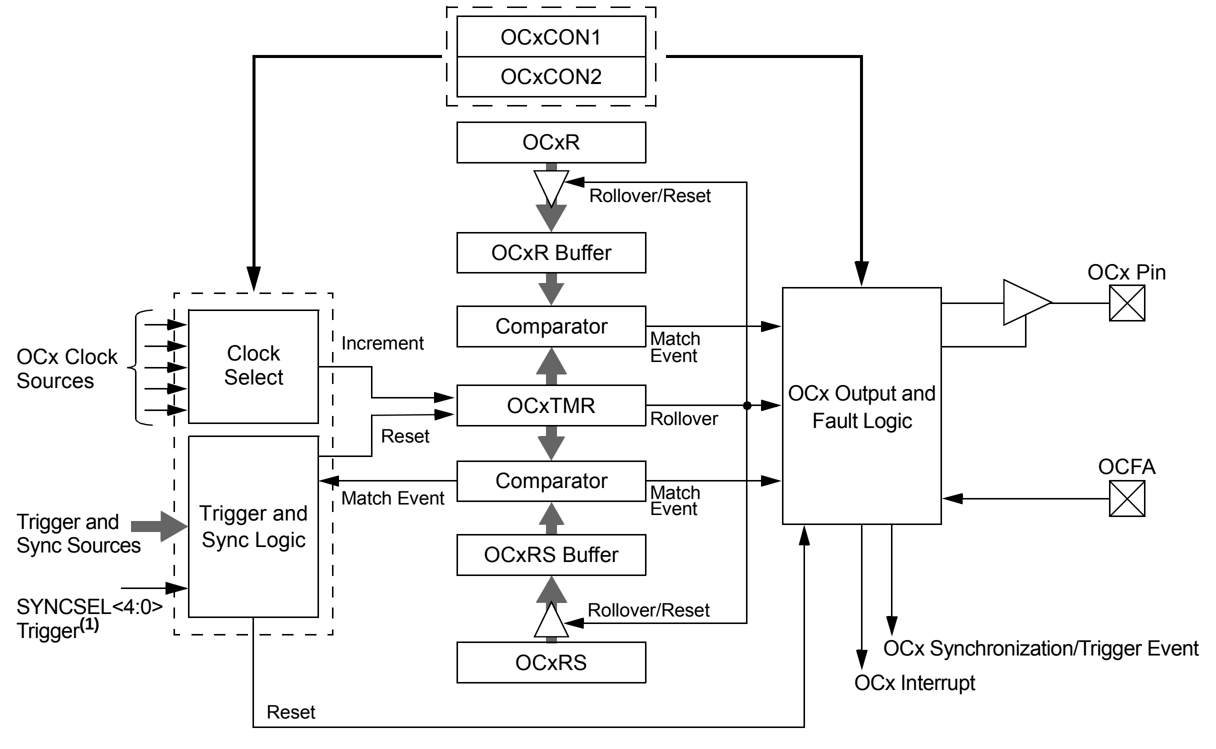
14.1 Output Compare Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page contains the latest updates and additional information.

14.1.1 KEY RESOURCES

- **"Output Compare with Dedicated Timer"** (DS70005159) in the *"dsPIC33/PIC24 Family Reference Manual"*
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related *"dsPIC33/PIC24 Family Reference Manual"* Sections
- Development Tools

FIGURE 14-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The trigger/sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the trigger/sync source must be changed to another source option.

REGISTER 15-8: SSEVTCMP: PWMx SECONDARY SPECIAL EVENT COMPARE REGISTER[1]

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEVTCMP<12:5>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
SSEVTCMP<4:0>					—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3	**SSEVTCMP<12:0>:** Special Event Compare Count Value bits
bit 2-0	**Unimplemented:** Read as ‘0’

Note 1: One LSB = 1.04 ns (at fastest auxiliary clock rate); therefore, the minimum SEVTCMP resolution is 8.32 ns.

REGISTER 15-9: CHOP: PWMx CHOP CLOCK GENERATOR REGISTER[1]

R/W-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
CHPCLKEN	—	—	—	—	—	CHOPCLK6	CHOPCLK5
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
CHOPCLK4	CHOPCLK3	CHOPCLK2	CHOPCLK1	CHOPCLK0	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15	**CHPCLKEN:** Enable Chop Clock Generator bit 1 = Chop clock generator is enabled 0 = Chop clock generator is disabled
bit 14-10	**Unimplemented:** Read as ‘0’
bit 9-3	**CHOPCLK<6:0>:** Chop Clock Divider bits Value is in 8.32 ns increments. The frequency of the chop clock signal is given by: Chop Frequency = 1/(16.64 * (CHOP<7:3> + 1) * Primary Master PWM Input Clock Period)
bit 2-0	**Unimplemented:** Read as ‘0’

Note 1: The chop clock generator operates with the primary PWMx clock prescaler (PCLKDIV<2:0>) in the PTCON2 register (Register 15-2).

REGISTER 15-20: IOCONx: PWMx I/O CONTROL REGISTER (x = 1 to 5) (CONTINUED)

bit 3-2	**CLDAT<1:0>:** State for PWMxH and PWMxL Pins if CLMOD is Enabled bits(2) IFLTMOD (FCLCONx<15>) = `0`: Normal Fault Mode: If current limit is active, then CLDAT1 provides the state for the PWMxH pin. If current limit is active, then CLDAT0 provides the state for the PWMxL pin. IFLTMOD (FCLCONx<15>) = `1`: Independent Fault Mode: CLDAT<1:0> bits are ignored.
bit 1	**SWAP:** SWAP PWMxH and PWMxL Pins bit `1` = PWMxH output signal is connected to the PWMxL pins; PWMxL output signal is connected to the PWMxH pins `0` = PWMxH and PWMxL pins are mapped to their respective pins
bit 0	**OSYNC:** Output Override Synchronization bit `1` = Output overrides via the OVRDAT<1:0> bits are synchronized to the PWMx time base `0` = Output overrides via the OVRDAT<1:0> bits occur on the next CPU clock boundary

Note 1: These bits should not be changed after the PWMx module is enabled (PTEN = `1`).

2: State represents the active/inactive state of the PWMx depending on the POLH and POLL bits settings.

REGISTER 15-21: TRIGx: PWMx PRIMARY TRIGGER COMPARE VALUE REGISTER (x = 1 to 5)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
TRGCMP<12:5>							
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
TRGCMP<4:0>					—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-3	**TRGCMP<12:0>:** Trigger Compare Value bits When the primary PWMx functions in the local time base, this register contains the compare values that can trigger the ADC module.
bit 2-0	**Unimplemented:** Read as ‘`0`’

REGISTER 19-8: ADCON4H: ADC CONTROL REGISTER 4 HIGH

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C3CHS1	C3CHS0	C2CHS1	C2CHS0	C1CHS1	C1CHS0	C0CHS1	C0CHS0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘`0`’

bit 7-6 **C3CHS<1:0>:** Dedicated ADC Core 3 Input Channel Selection bits

`1x` = Reserved
`01` = AN15 (differential negative input when DIFF3 (ADMOD0L<7>) = `1`)
`00` = AN3

bit 5-4 **C2CHS<1:0>:** Dedicated ADC Core 2 Input Channel Selection bits

`11` = Reserved
`10` = VREF Band Gap
`01` = AN11 (differential negative input when DIFF2 (ADMOD0L<5>) = `1`)
`00` = AN2

bit 3-2 **C1CHS<1:0>:** Dedicated ADC Core 1 Input Channel Selection bits

`11` = AN1ALT
`10` = PGA2
`01` = AN18 (differential negative input when DIFF1 (ADMOD0L<3>) = `1`)
`00` = AN1

bit 1-0 **C0CHS<1:0>:** Dedicated ADC Core 0 Input Channel Selection bits

`11` = AN0ALT
`10` = PGA1
`01` = AN7 (differential negative input when DIFF0 (ADMOD0L<1>) = `1`)
`00` = AN0

21.1 Module Description

The Programmable Gain Amplifiers are used to amplify small voltages (i.e., voltages across burden/shunt resistors) to improve the signal-to-noise ratio of the measured signal. The PGAx output voltage can be read by any of the four dedicated Sample-and-Hold circuits on the ADC module. The output voltage can also be fed to the comparator module for overcurrent/ voltage protection. Figure 21-2 shows a functional block diagram of the PGAx module. Refer to **Section 19.0 "High-Speed, 12-Bit Analog-to-Digital Converter (ADC)"** and **Section 20.0 "High-Speed Analog Comparator"** for more interconnection details.

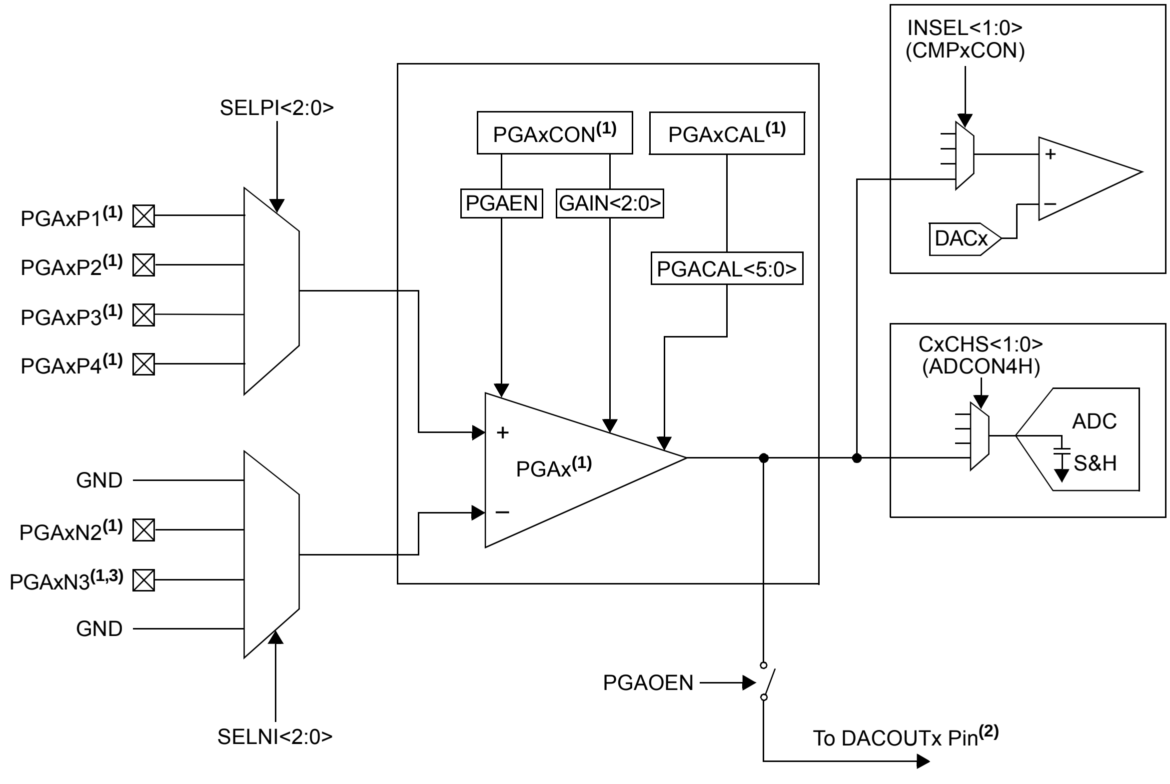
The gain of the PGAx module is selectable via the GAIN<2:0> bits in the PGAxCON register. There are five selectable gains, ranging from 4x to 64x. The SELPI<2:0> and SELNI<2:0> bits in the PGAxCON register select one of four positive/negative inputs to the PGAx module. For single-ended applications, the SELNI<2:0> bits will select the ground as the negative input source. To provide an independent ground reference, PGAxN2 and PGAxN3 pins are available as the negative input source to the PGAx module.

Note 1:	Not all PGA positive/negative inputs are available on all devices. Refer to the specific device pinout for available input source pins.

The output voltage of the PGAx module can be connected to the DACOUTx pin by setting the PGAOEN bit in the PGAxCON register. When the PGAOEN bit is enabled, the output voltage of PGA1 is connected to DACOUT1 and PGA2 is connected to DACOUT2. For devices with a single DACOUTx pin, the output voltage of PGA2 can be connected to DACOUT1 by configuring the DBCC Configuration bit in the FDEVOPT register (FDEVOPT<6>).

If both the DACx output voltage and PGAx output voltage are connected to the DACOUTx pin, the resulting output voltage would be a combination of signals. There is no assigned priority between the PGAx module and the DACx module.

FIGURE 21-2: PGAx FUNCTIONAL BLOCK DIAGRAM



Note 1: x = 1 and 2.
2: The DACOUT2 device pin is only available on 64-pin devices.
3: The PGAxN3 input is not available on 28-pin devices.

23.0 SPECIAL FEATURES

> **Note:** This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

The dsPIC33EPXXGS50X family devices include several features intended to maximize application flexibility and reliability, and minimize cost through elimination of external components. These are:

- Flexible Configuration
- Watchdog Timer (WDT)
- Code Protection and CodeGuard™ Security
- JTAG Boundary Scan Interface
- In-Circuit Serial Programming™ (ICSP™)
- In-Circuit Emulation
- Brown-out Reset (BOR)

23.1 Configuration Bits

In dsPIC33EPXXGS50X family devices, the Configuration Words are implemented as volatile memory. This means that configuration data must be programmed each time the device is powered up. Configuration data is stored at the end of the on-chip program memory space, known as the Flash Configuration Words. Their specific locations are shown in Table 23-1 with detailed descriptions in Table 23-2. The configuration data is automatically loaded from the Flash Configuration Words to the proper Configuration Shadow registers during device Resets.

For devices operating in Dual Partition modes, the BSEQx bits (FBTSEQ<11:0>) determine which panel is the Active Partition at start-up and the Configuration Words from that panel are loaded into the Configuration Shadow registers.

> **Note:** Configuration data is reloaded on all types of device Resets.

When creating applications for these devices, users should always specifically allocate the location of the Flash Configuration Words for configuration data in their code for the compiler. This is to make certain that program code is not stored in this address when the code is compiled. Program code executing out of configuration space will cause a device Reset.

> **Note:** Performing a page erase operation on the last page of program memory clears the Flash Configuration Words.

TABLE 24-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles[1]	Status Flags Affected
74	`SL`	`SL f`	f = Left Shift f	1	1	C,N,OV,Z
		`SL f,WREG`	WREG = Left Shift f	1	1	C,N,OV,Z
		`SL Ws,Wd`	Wd = Left Shift Ws	1	1	C,N,OV,Z
		`SL Wb,Wns,Wnd`	Wnd = Left Shift Wb by Wns	1	1	N,Z
		`SL Wb,#lit5,Wnd`	Wnd = Left Shift Wb by lit5	1	1	N,Z
75	`SUB`	`SUB Acc`	Subtract Accumulators	1	1	OA,OB,OAB, SA,SB,SAB
		`SUB f`	f = f – WREG	1	1	C,DC,N,OV,Z
		`SUB f,WREG`	WREG = f – WREG	1	1	C,DC,N,OV,Z
		`SUB #lit10,Wn`	Wn = Wn – lit10	1	1	C,DC,N,OV,Z
		`SUB Wb,Ws,Wd`	Wd = Wb – Ws	1	1	C,DC,N,OV,Z
		`SUB Wb,#lit5,Wd`	Wd = Wb – lit5	1	1	C,DC,N,OV,Z
76	`SUBB`	`SUBB f`	f = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB f,WREG`	WREG = f – WREG – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB #lit10,Wn`	Wn = Wn – lit10 – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB Wb,Ws,Wd`	Wd = Wb – Ws – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBB Wb,#lit5,Wd`	Wd = Wb – lit5 – $(\overline{C})$	1	1	C,DC,N,OV,Z
77	`SUBR`	`SUBR f`	f = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR f,WREG`	WREG = WREG – f	1	1	C,DC,N,OV,Z
		`SUBR Wb,Ws,Wd`	Wd = Ws – Wb	1	1	C,DC,N,OV,Z
		`SUBR Wb,#lit5,Wd`	Wd = lit5 – Wb	1	1	C,DC,N,OV,Z
78	`SUBBR`	`SUBBR f`	f = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR f,WREG`	WREG = WREG – f – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR Wb,Ws,Wd`	Wd = Ws – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
		`SUBBR Wb,#lit5,Wd`	Wd = lit5 – Wb – $(\overline{C})$	1	1	C,DC,N,OV,Z
79	`SWAP`	`SWAP.b Wn`	Wn = nibble swap Wn	1	1	None
		`SWAP Wn`	Wn = byte swap Wn	1	1	None
80	`TBLRDH`	`TBLRDH Ws,Wd`	Read Prog<23:16> to Wd<7:0>	1	5	None
81	`TBLRDL`	`TBLRDL Ws,Wd`	Read Prog<15:0> to Wd	1	5	None
82	`TBLWTH`	`TBLWTH Ws,Wd`	Write Ws<7:0> to Prog<23:16>	1	2	None
83	`TBLWTL`	`TBLWTL Ws,Wd`	Write Ws to Prog<15:0>	1	2	None
84	`ULNK`	`ULNK`	Unlink Frame Pointer	1	1	SFA
85	`XOR`	`XOR f`	f = f .XOR. WREG	1	1	N,Z
		`XOR f,WREG`	WREG = f .XOR. WREG	1	1	N,Z
		`XOR #lit10,Wn`	Wd = lit10 .XOR. Wd	1	1	N,Z
		`XOR Wb,Ws,Wd`	Wd = Wb .XOR. Ws	1	1	N,Z
		`XOR Wb,#lit5,Wd`	Wd = Wb .XOR. lit5	1	1	N,Z
86	`ZE`	`ZE Ws,Wnd`	Wnd = Zero-extend Ws	1	1	C,Z,N

Note 1: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

26.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the dsPIC33EPXXGS50X family electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXGS50X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these, or any other conditions above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias	-40°C to +125°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to VSS(3)	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3)	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when VDD < 3.0V(3)	-0.3V to +3.6V
Maximum current out of VSS pin	300 mA
Maximum current into VDD pin(2)	300 mA
Maximum current sunk/sourced by any 4x I/O pin	15 mA
Maximum current sunk/sourced by any 8x I/O pin	25 mA
Maximum current sunk by all ports(2)	200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those, or any other conditions above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 26-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

TABLE 26-14: DC CHARACTERISTICS: PROGRAM MEMORY

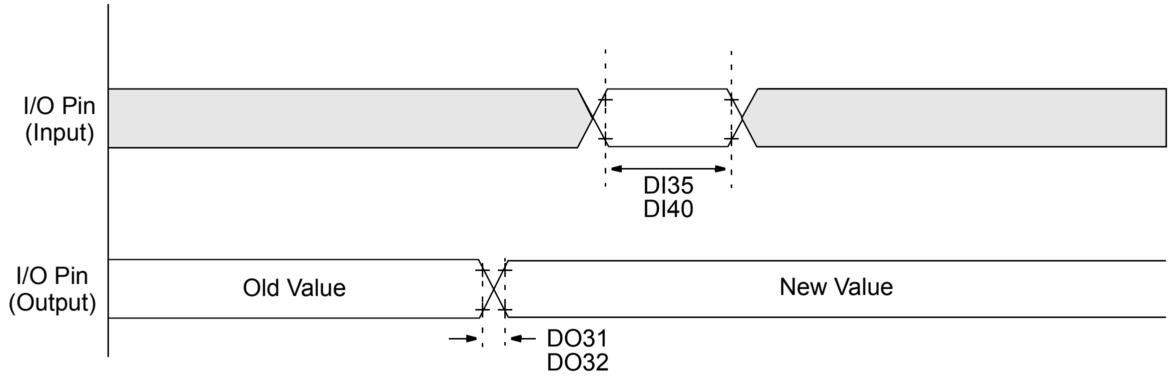
DC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V** **(unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.[1]**	**Max.**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000	—	—	E/W	-40°C to +125°C
D131	VPR	VDD for Read	3.0	—	3.6	V	
D132b	VPEW	VDD for Self-Timed Write	3.0	—	3.6	V	
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated, -40°C to +125°C
D135	IDDP	Supply Current during Programming[2]	—	10	—	mA	
D136	IPEAK	Instantaneous Peak Current During Start-up	—	—	150	mA	
D137a	TPE	Page Erase Time	19.7	—	20.1	ms	TPE = 146893 FRC cycles, TA = +85°C **(Note 3)**
D137b	TPE	Page Erase Time	19.5	—	20.3	ms	TPE = 146893 FRC cycles, TA = +125°C **(Note 3)**
D138a	TWW	Word Write Cycle Time	46.5	—	47.3	µs	TWW = 346 FRC cycles, TA = +85°C **(Note 3)**
D138b	TWW	Word Write Cycle Time	46.0	—	47.9	µs	TWW = 346 FRC cycles, TA = +125°C **(Note 3)**
D139a	TRW	Row Write Time	667	—	679	µs	TRW = 4965 FRC cycles, TA = +85°C **(Note 3)**
D139b	TRW	Row Write Time	660	—	687	µs	TRW = 4965 FRC cycles, TA = +125°C **(Note 3)**

Note 1: Data in “Typ.” column is at 3.3V, +25°C unless otherwise stated.

2: Parameter characterized but not tested in manufacturing.

3: Other conditions: FRC = 7.37 MHz, TUN<5:0> = `011111` (for Minimum), TUN<5:0> = `100000` (for Maximum). This parameter depends on the FRC accuracy (see Table 26-20) and the value of the FRC Oscillator Tuning register (see Register 8-4). For complete details on calculating the Minimum and Maximum time, see **Section 5.3 “Programming Operations”**.

FIGURE 26-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-22: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.[1]**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in “Typ.” column is at 3.3V, +25°C unless otherwise stated.

FIGURE 26-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS

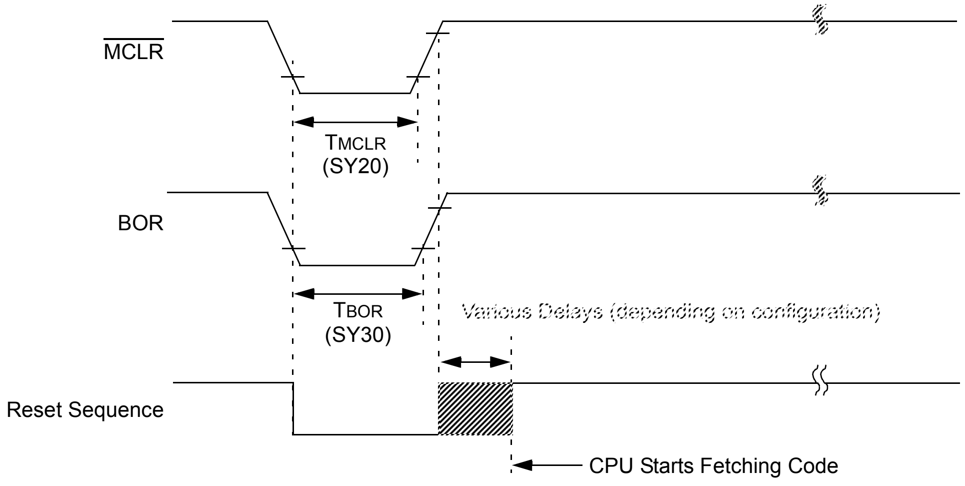
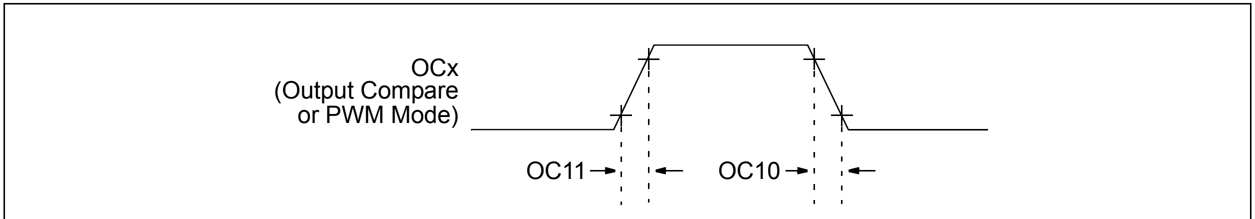


FIGURE 26-7: OUTPUT COMPARE x MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 26-1 for load conditions.

TABLE 26-28: OUTPUT COMPARE x MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See Parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See Parameter DO31

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 26-8: OCx/PWMx MODULE TIMING CHARACTERISTICS

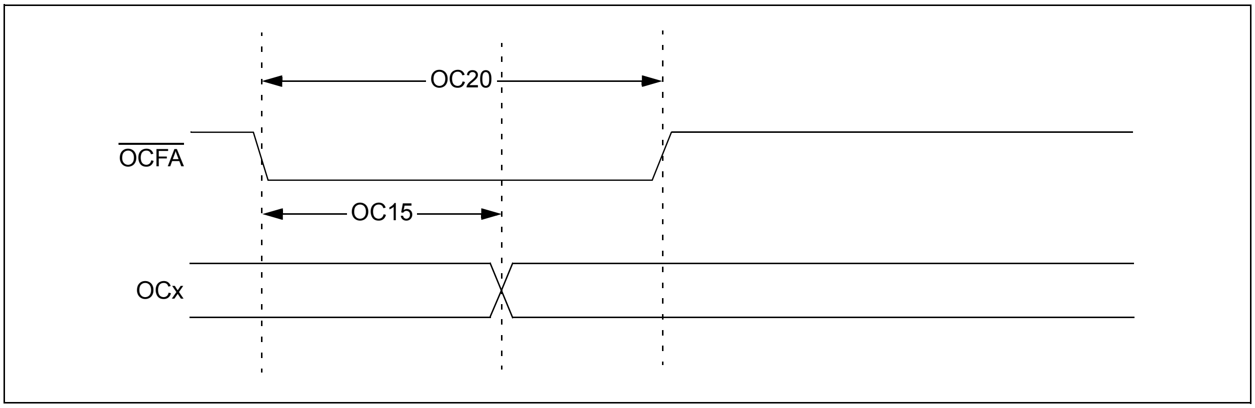


TABLE 26-29: OCx/PWMx MODULE TIMING REQUIREMENTS

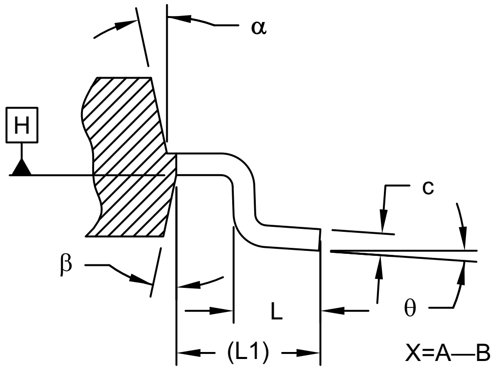
AC CHARACTERISTICS			**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic[1]**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWMx I/O Change	—	—	TCY + 20	ns	
OC20	TFLT	Fault Input Pulse Width	TCY + 20	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

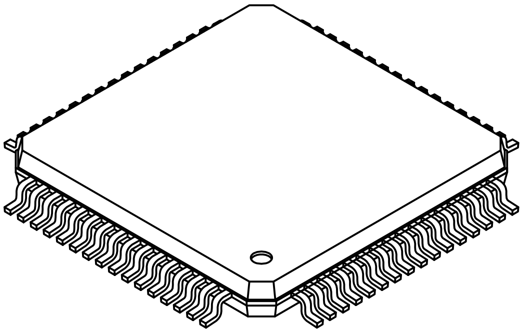
NOTES:

64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

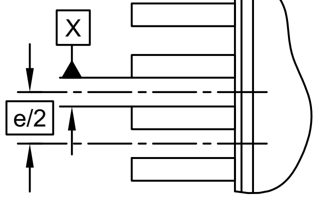
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A



X=A—B OR D



DETAIL 1

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	64		
Lead Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	12.00 BSC		
Overall Length	D	12.00 BSC		
Molded Package Width	E1	10.00 BSC		
Molded Package Length	D1	10.00 BSC		
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

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